

Response
Serial No. 10/670,377
Attorney Docket No. 990675B

REMARKS

Claim 20 is pending in the present application. By this Amendment, claim 20 has been amended. No new matter has been added. It is respectfully submitted that this Amendment is fully responsive to the Office Action dated January 14, 2005.

As to the Merits:

As to the merits of this case, the Examiner sets forth the following rejection:

Claim 20 stands rejected under 35 USC §102(b) as being anticipated by Lum et al. (U.S. Patent No. 5,534,784).

This rejection is respectfully traversed.

Claim 20, as amended, now calls for *a method of testing a device, comprising the step of: electrically connecting electrode pads of a device testing contactor to electrodes of a device being tested; the electrode pads being formed on a membrane-type flexible wiring board of the device testing contactor, and being reinforced by a reinforcing member, and the device testing contactor comprising the wiring board and the reinforcing member collectively molded and bonded to each other.*

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Lum et al discloses in FIGs. 2 and 3 that the probe wires 84 of the probe head 68 are electrically connected to the conductive bumps 54 of the semiconductor die 52, the probe wires 84 being formed on the housing 86 of the probe head 68.

However, the probing method of Lum et al. is directed to the use of the array probe head 68 having the probe wires 84 for coupling the conductive pads on the production package substrate 64 with the conductive bumps 54 on the semiconductor die 52, and the use of the substrate 64 interposed between the probe card 62 and the probe head 68, the substrate 64 being configured to have conductive pads 78 matching the pads 74 on the probe card 62 and to have conductive pads 80 matching the probe wires 84 connected to the bumps 54 on the die 52.

It is respectfully submitted that clearly Lum et al. do not disclose that the wiring board 86 (the housing of the probe head 68) and the elements 62, 64, 66 are collectively molded and bonded to each other as recited in the amended claim 20. In contrast to the teaching of Lum et al., the applicants disclose that the first reinforcing member 12A bonded to the rear surface of the wiring board 11 is collectively molded with the wiring board as disclosed on pages 7-8 of the present specification.

Moreover, it is submitted that clearly Lum et al. do not disclose that the wiring board 86 is a membrane-type flexible wiring board as recited in the amended claim 20. In contrast, the

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applicants disclose that the wiring board 11A is a membrane-type wiring board with flexibility as disclosed on page 7, lines 24-25 of the present specification.

For at least the above-mentioned reasons, it is believed that Lum et al. clearly do not disclose or suggest the applicants' claimed device testing method. As such, it is respectfully requested that the Examiner reconsider the case in view of the above arguments and withdraw the rejection from the application.

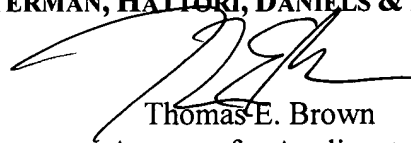
In view of the aforementioned amendments and accompanying remarks, Applicants submit that that the claims, as herein amended, are in condition for allowance. Applicants request such action at an early date.

If the Examiner believes that this application is not now in condition for allowance, the Examiner is requested to contact Applicants' undersigned attorney to arrange for an interview to expedite the disposition of this case.

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If this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,
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